

PRESSURE SENSITIVE ADHESIVE COMPOSITION AND USE THEREOF**ABSTRACT**

A pressure sensitive adhesive composition comprising:

(A) a carboxyl group containing copolymer obtained by solution polymerization of (a) a carboxyl group containing polymerizable monomer and (b) another monomer
5 copolymerizable with the monomer (a);

(B) a neutralizer; and

(C) a crosslinking agent. This pressure sensitive adhesive composition is suitable for use in a wafer surface
10 protective sheet employed for protecting a circuit pattern formed on a wafer surface from cutting debris, etc. at the time of polishing the back of the wafer. When this pressure sensitive adhesive composition is used, not only is the voltage of peel electrification extremely low at the
15 time of stripping of the pressure sensitive adhesive sheet but also, even if the pressure sensitive adhesive remains on the wafer surface, the residual pressure sensitive adhesive can easily be removed by washing with water.